ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc nternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lower	level p	arts, the	declaratio	n encomp	asses all		aterials for	r which th	e item is an assembly ne manufacturer has leclaration.		
1752-2 1.1	_	Web Site for Informat		-1752 Standa	rd		n Type * ribute			laration Class * ss 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa						
Supplier Information																
Company Name *		Company Unique ID		Unique ID Au	Unique ID Authority			Response Date *			Response Document ID					
Anaren Microwave						2020-1	2-14									
Contact Name * Title - Contact				Phone - Contact *			- Contac	t *								
Herbert Jones	Project Engineer		315-233-551	0 her		herbert.jones@ttm.com			Duplic	ate Contac	t -> Auth	orized Re	epresentative			
Authorized Representative * Title - Representative			9	Phone - Representative *			Email - Representative *				Supplier Comments or URL for Additional Information					
Herbert Jones Project Eng		Project Engineer		315-233-551	0	herbert.jones@ttm.com			ո							
Requester Item Number		Mfr Item Number		Mfr Item Name	Effectiv	e Date	Version	Manufact	facturing Site Weight *		UOM		Unit Type			
		C200N50Z4B		Surface Mour	nt Termination, 20	2020-1	2-14	A	East Syra	acuse	0.28311	g		Each		
Alternate Recommenda	ation				Alternate Item C			Item Com								
Manufacturing Proces	ss In	formation		L												
Terminal Plating / Grid Array Material Terminal B			ase Alloy	ating Peak Process Body Tempe			Temperati	erature Max Time at Peak Temperature Number of Reflow								
Matte Tin (Sn) - with Nickel (Ni) barrier CU Alloy			1	260			260 C	C 30 se			conds 3					
Comments Compliant to RoHS 2 Dir	ectiv	e 2011/65/EU of the	Europear	n Parliament	and of the Counc	il of 8 、	June 201	1 & Com	mission	Delegate	d Directive 2	015/863/I	EU of 31	March 2015.		

Save the fields in Import fields from a Clear all of the Lock the fields on this **Export Data** Import Data Reset Form Lock Supplier Fields this form to a file file into this form fields on this form form to prevent changes **RoHS Material Composition Declaration Declaration Type *** Custom Rohs Directive Rohs Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenvls (PBB). Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium 2002/95/EC RoHS 2 (Directive 2011/65/EU & 2015/863/EU) Definition Addendum: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. Supplier Acceptance * Accepted 1 - Item(s) does not contain RoHS restricted substances per the definition above **RoHS Declaration *** Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. **Declaration Signature**

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	14 / - 1 - 1 - 4	Unit of		Laval	Substance Catanani			Cubatanas	CAS	Fuament	Mainba	Unit of	Tolera	nce	DDM
	Name		Material	Weight	Measure		Level	Substance Category			Substance	CAS	Exempt	Weight	Measure	-	+ '	PPM
+1 -1	C200N50Z4B	+M -M	Part Marking Ink	0.00002	0 g	+C -C	Supplier	Part Marking Ink	+S	Ş	Titanium dioxide (TiO2)	13463-67-7		0.000017	g		8	57,10
						+C -C	Supplier	Part Marking Ink	+S	-S	Silica amorphous (SiO2	7631-86-9		0.000002	g		1.	42,90
		+M -M	Protective Glaze	0.00593	5 g	+C -C	Supplier	Protective Glaze	+S	Ģ	Boron Oxide (BO)	1303-86-2		0.000492	g		8:	3,027
						+C -C	Supplier	Protective Glaze	+S	-S	Aluminum Oxide (Al2O3	1344-28-1		0.000147	g		2	24,912
						+C -C	Supplier	Protective Glaze	+S	-S	Silicon Dioxide (SiO2)	14808-60-7		0.000147	g		2	24,912
						+C -C	Supplier	Protective Glaze	+S	-S	*Proprietary Metal Com	Proprietary		0.000363	g		6	1,256
						+C -C	Supplier	Protective Glaze	+S	-S	*Proprietary Blue Pigme	Proprietary		0.000727	g		1:	22,51
						+C -C	Supplier	Protective Glaze	+S	-S	Chromium(III) oxide (Cr	1308-38-9		0.000032	g		5	5,501.6
						+C -C	Supplier	Protective Glaze	+S	-S	Cobalt (Co)	7440-48-4		0.001090	g		1	83,76
						+C -C	Supplier	Protective Glaze	+S	-S	Molybdenum (Mo)	7439-98-7		0.001454	g		2	245,02
						+C -C	Supplier	Protective Glaze	+S	-S	Zinc oxide (ZnO)	1314-13-2		0.001478	g		2	249,08
		+M -M	Thick Film Resis	0.00139	3 g	+C -C	Supplier	Thick Film Resistor	+S	-S	Boron Oxide (BO)	1303-86-2		0.000187	g		1:	34,60
						+C -C	Supplier	Thick Film Resistor	+S	-S	Magnesium Oxide (MgO	1309-48-4		0.000134	g		9	6,200
						+C -C	Supplier	Thick Film Resistor	+S	-S	Aluminum Oxide (Al2O3	1344-28-1		0.000187	g		1	34,60
						+C -C	Supplier	Thick Film Resistor	+S	-S	Silicon Dioxide (SiO2)	14808-60-7		0.000071	g		5	1,300
						+C -C	Supplier	Thick Film Resistor	+S	-S	Ruthenium(IV) dioxide (12036-10-1		0.000688	g		4	93,60
						+C -C	Supplier	Thick Film Resistor	+S	-S	Zinc oxide (ZnO)	1314-13-2		0.000125	g		8	9,700
		+M -M	Conductor	0.00858	3 g	+C -C	Supplier	Conductor	+S	-S	Silver (Ag)	7440-22-4		0.007810	g		9	10,00
						+C -C	Supplier	Conductor	+S	-S	Cobalt (Co)	7440-48-4		0.000128	g		1	5,000
						+C -C	Supplier	Conductor	+S	-S	Titanium (Ti)	7440-32-6		0.000643	g		7	5,000
		+M -M	Substrate	0.262820	O g	+C -C	Supplier	Substrate	+S	-S	Aluminum Nitride (ALN	24304-00-5		0.249679	g		9	50,00
						+C -C	Supplier	Substrate	+S	-s	Yttrium (III) oxide (Y2O3	1314-36-9		0.013141	g		5	60,000
		+M -M	Nickel Plating	0.00331	6 g	+C -C	A	Lead/Lead Compound	+S	-S	Lead	7439-92-1		0.00000	g		4	199.75

		+C -C B	Nickel (external applic	+S ·	-S	Nickel	7440-02-0	0.003314	g		999,50
+M -M Tin Plating	0.001034g	+C -C Supplier	Tin Plating	+8 -	-s	Tin (Sn)	7440-31-5	0.001034	g		1,000,0